



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Wen-Chou Vincent Wang, *et al.*

Attorney Docket No.:
ALTRP096/A1201

Application No.: 10/719,451

Examiner: Jasmine Jhihan B. Clark

Filed: November 20, 2003

Group: 2815

Title: STRUCTURE AND MATERIAL FOR
ASSEMBLING A LOW-K SI DIE TO ACHIEVE A
LOW WARPAGE AND INDUSTRIAL GRADE
RELIABILITY FLIP CHIP PACKAGE WITH
ORGANIC SUBSTRATE

CERTIFICATE OF MAILING
I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first-class mail on January 24, 2005 in an envelope addressed to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

Signed: 

Tomika D. Thomas

**INFORMATION DISCLOSURE STATEMENT
37 CFR §§1.56 AND 1.97(b)**

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

The references listed in the attached PTO Form 1449, copies of which are attached, may be material to examination of the above-identified patent application. Applicants submit these references in compliance with their duty of disclosure pursuant to 37 CFR §§1.56 and 1.97. The Examiner is requested to make these references of official record in this application.

This Information Disclosure Statement is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that these references indeed constitute prior art.

This Information Disclosure Statement is: (i) filed within three (3) months of the filing date of the above-referenced application, (ii) believed to be filed before the mailing date of a first Office Action on the merits, or (iii) believed to be filed before the mailing of a first Office Action after the filing of a Request for Continued Examination under §1.114. Accordingly, it is

believed that no fees are due in connection with the filing of this Information Disclosure Statement. However, if it is determined that any fees are due, the Commissioner is hereby authorized to charge such fees to Deposit Account 500388 (Order No. ALTRP096).

Respectfully submitted,
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Patent Application 1449 (Modified)

**Information Disclosure
Statement By Applicant**

(Use Several Sheets if Necessary)

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10/719,451

Applicant:

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U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
	A1	6,617,683	09/2003	Lebonheur, <i>et al.</i>			
	A2	6,504,242	01/2003	Deppisch, <i>et al.</i>			
	A3	6,756,685	06/2004	Tao, Tetsuya			
	A4	6,262,489	07/2001	Koors, <i>et al.</i>			
	A5	6,773,963	08/2004	Houle, Sabina J.			
	A6	5,909,056	06/1999	Mertol, Atila			
	A7	6,091,603	07/2000	Daves, <i>et al.</i>			
	A8	6,472,762	10/2002	Kutlu, Zafer S.			
	A9	6,744,132	06/2004	Alcoe, <i>et al.</i>			
	A10	6,103,550	08/2000	Camenforte, <i>et al.</i>			

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	C1	U.S. Patent Application, Serial No.: 10/849,651 filed May 19, 2004 entitled: <i>Low Stress And Warpage Laminate Flip Chip BGA Package</i>
Examiner		Date Considered

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.